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MULTILAYER COMMON MODE CHOKE COILS(MC SERIES F TYPE)



REFLOW

■ PARTS NUMBER

* Operating Temp.: -40~+85°C

M	C	F	0	8	0	6	2	G	1	2	0	-	T	△
①			②				③	④			⑤		⑥	⑦

△=Blank space

①Series name

Code	Series name
MCF	Multilayer common mode choke coil

②Dimensions

Code	Dimensions [mm]
0605	0.65 × 0.50
0806	0.85 × 0.65
1210	1.25 × 1.0
2010	2.0 × 1.0

③No. of Lines

Code	No. of Lines
2	2 lines
4	4 lines

④Material

Code	Material
G	Refer to impedance curves for material differences
E	
H	

⑤Nominal common impedance

Code (example)	Nominal common impedance [Ω]
120	12
900	90

⑥Packaging

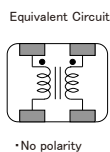
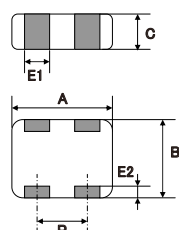
Code	Packaging
-T	Taping

⑦Internal code

Code	Internal code
△	Standard

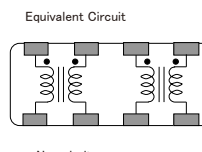
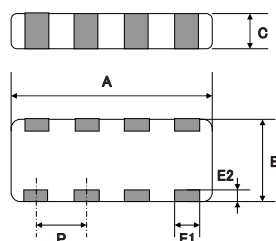
■ STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY / EQUIVALENT CIRCUIT

2 LINES



*No polarity

4 LINES



*No polarity

Type	A	B	C	E1	E2	P	Standard quantity [pcs] Taping
MCF0605	0.65±0.05 (0.026±0.002)	0.50±0.05 (0.020±0.002)	0.30±0.05 (0.012±0.002)	0.15±0.1 (0.006±0.004)	0.12±0.1 (0.005±0.004)	0.40±0.10 (0.016±0.004)	15000
MCF0806	0.85±0.05 (0.033±0.002)	0.65±0.05 (0.026±0.002)	0.40±0.05 (0.016±0.002)	0.27±0.1 (0.011±0.004)	0.2 +0.05/-0.1 (0.008 +0.002/-0.004)	0.50±0.10 (0.020±0.004)	10000
MCF1210	1.0±0.15 (0.039±0.006)	1.25±0.15 (0.049±0.006)	0.55±0.1 (0.022±0.004)	0.3±0.1 (0.012±0.004)	0.2±0.1 (0.008±0.004)	0.55±0.10 (0.022±0.004)	5000
MCF2010	2.0±0.15 (0.079±0.006)	1.0±0.15 (0.039±0.006)	0.45±0.1 (0.018±0.004)	0.25 +0.15/-0.1 (0.010 +0.006/-0.004)	0.25±0.15 (0.010±0.006)	0.50±0.10 (0.020±0.004)	4000

Unit: mm (inch)

NOISE SUPPRESSION COMPONENTS / COMMON MODE CHOKE COILS

PARTS NUMBER

MCF0605 type

Parts number	EHS	No. of Lines	Common mode impedance [Ω]	Measuring frequency [MHz]	DC Resistance [Ω] (max.)	Rated current [A] (max.)	Rated voltage [V]	Insulation resistance [MΩ] (min.)
MCF0605 2G120-T	RoHS	2	12±5	100	2.5	0.05	5	100
MCF0605 2G350-T	RoHS	2	35±20%	100	6.5	0.05	5	100
MCF0605 2E600-T	RoHS	2	60±25%	100	4.75	0.05	5	100
MCF0605 2E900-T	RoHS	2	90±25%	100	3.9	0.05	5	100

MCF0806 type

Parts number	EHS	No. of Lines	Common mode impedance [Ω]	Measuring frequency [MHz]	DC Resistance [Ω] (max.)	Rated current [A] (max.)	Rated voltage [V]	Insulation resistance [MΩ] (min.)
MCF0806 2G120-T	RoHS	2	12±5	100	2.5	0.13	5	100
MCF0806 2G470-T	RoHS	2	47±20%	100	4.0	0.10	5	100
MCF0806 2G900-T	RoHS	2	90±20%	100	5.0	0.10	5	100
MCF0806 2E300-T	RoHS	2	30±25%	100	1.5	0.15	5	100

MCF1210 type

Parts number	EHS	No. of Lines	Common mode impedance [Ω]	Measuring frequency [MHz]	DC Resistance [Ω] (max.)	Rated current [A] (max.)	Rated voltage [V]	Insulation resistance [MΩ] (min.)
MCF1210 2G400-T	RoHS	2	40±25%	100	2.5	0.10	5	100
MCF1210 2G900-T	RoHS	2	90±25%	100	4.5	0.10	5	100
MCF1210 2H900-T	RoHS	2	90±20%	100	2.5	0.15	5	100

MCF2010 type

Parts number	EHS	No. of Lines	Common mode impedance [Ω]	Measuring frequency [MHz]	DC Resistance [Ω] (max.)	Rated current [A] (max.)	Rated voltage [V]	Insulation resistance [MΩ] (min.)
MCF2010 4G900-T	RoHS	4	90±25%	100	4.5	0.10	5	100

Multilayer chip inductors

Multilayer chip inductors for high frequency, Multilayer chip bead inductors

Multilayer common mode choke coils (MC series F type)

Metal Multilayer Chip Power Inductors (MCOIL™ MC series)

PACKAGING

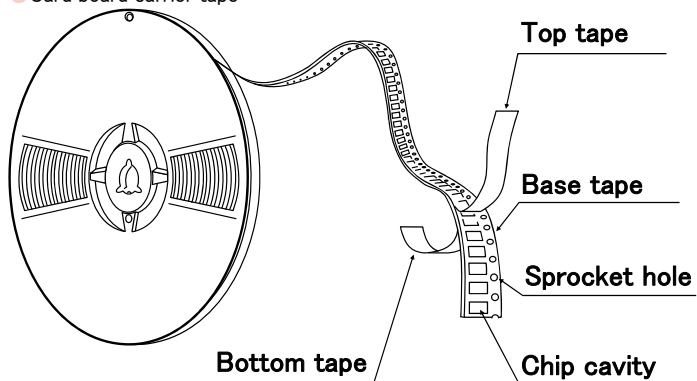
① Minimum Quantity

● Tape & Reel Packaging

Type	Thickness mm (inch)	Standard Quantity [pcs]	
		Paper Tape	Embossed Tape
CK1608 (0603)	0.8 (0.031)	4000	—
CK2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
CKS2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
CKP1608 (0603)	0.8 (0.031)	4000	—
CKP2012 (0805)	0.9 (0.035)	—	3000
CKP2016 (0806)	0.9 (0.035)	—	3000
CKP2520 (1008)	0.7 (0.028)	—	3000
	0.9 (0.035)	—	3000
	1.1 (0.043)	—	2000
NM2012 (0805)	0.9 (0.035)	—	3000
NM2520 (1008)	0.9 (0.035)	—	3000
	1.1 (0.043)	—	2000
LK1005 (0402)	0.5 (0.020)	10000	—
LK1608 (0603)	0.8 (0.031)	4000	—
LK2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
HK0603 (0201)	0.3 (0.012)	15000	—
HK1005 (0402)	0.5 (0.020)	10000	—
HK1608 (0603)	0.8 (0.031)	4000	—
HK2125 (0805)	0.85 (0.033)	—	4000
	1.0 (0.039)	—	3000
HKQ0402 (01005)	0.2 (0.008)	20000	40000
HKQ0603W (0201)	0.3 (0.012)	15000	—
HKQ0603C (0201)	0.3 (0.012)	15000	—
HKQ0603S (0201)	0.3 (0.012)	15000	—
HKQ0603U (0201)	0.3 (0.012)	15000	—
AQ105 (0402)	0.5 (0.020)	10000	—
BK0402 (01005)	0.2 (0.008)	20000	—
BK0603 (0201)	0.3 (0.012)	15000	—
BK1005 (0402)	0.5 (0.020)	10000	—
BKH0603 (0201)	0.3 (0.012)	15000	—
BKH1005 (0402)	0.5 (0.020)	10000	—
BK1608 (0603)	0.8 (0.031)	4000	—
BK2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
BK2010 (0804)	0.45 (0.018)	4000	—
BK3216 (1206)	0.8 (0.031)	—	4000
BKP0402 (01005)	0.2 (0.008)	20000	—
BKP0603 (0201)	0.3 (0.012)	15000	—
BKP1005 (0402)	0.5 (0.020)	10000	—
BKP1608 (0603)	0.8 (0.031)	4000	—
BKP2125 (0805)	0.85 (0.033)	4000	—
MCF0605 (0202)	0.3 (0.012)	15000	—
MCF0806 (0302)	0.4 (0.016)	—	10000
MCF1210 (0504)	0.55 (0.022)	—	5000
MCF2010 (0804)	0.45 (0.018)	—	4000
MCFE1608 (0603)	0.65 (0.026)	4000	—
MCKK2012 (0805)	1.00 (0.039)	—	3000

②Taping material

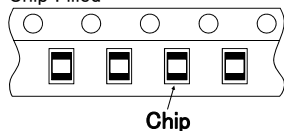
● Card board carrier tape



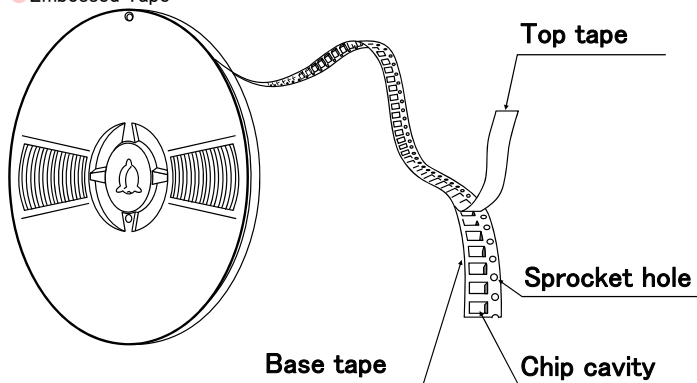
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CKP	1608
CK	2125
CKS	2125
LK	1005
LK	1608
LK	2125
HK	0603
HK	1005
HK	1608
HKQ	0402
HKQ	0603
AQ	105

BK	0402
BK	0603
BK	1005
BK	1608
BK	2125
BK	2010
BKP	0402
BKP	0603
BKP	1005
BKP	1608
BKP	2125
BKH	0603
BKH	1005
MCF	0605
MC	1608

Chip Filled



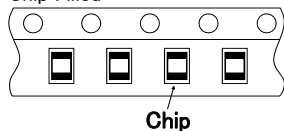
● Embossed Tape



CK	2125
CKS	2125
CKP	2012
CKP	2016
CKP	2520
NM	2012
NM	2520
LK	2125
HKQ	0402
HK	2125

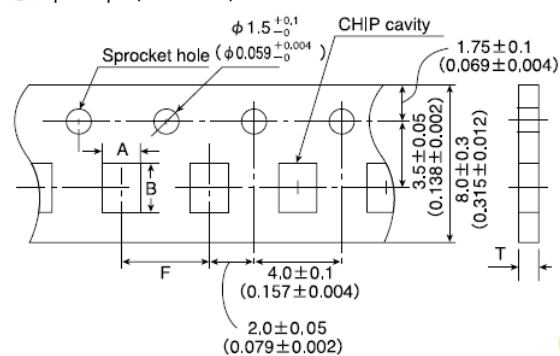
BK	2125
BK	3216
MCF	0806
MCF	1210
MCF	2010
MC	2012

Chip Filled



③Taping Dimensions

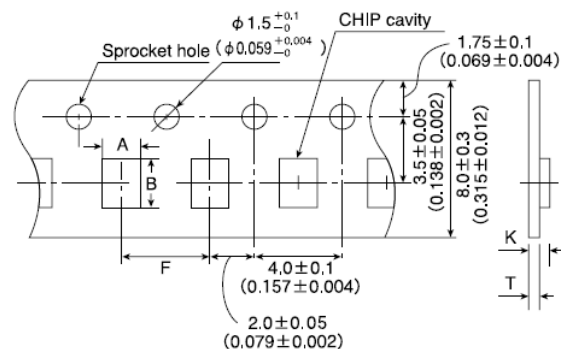
● Paper tape (8mm wide)



Type	Thickness mm (inch)	Chip cavity		Insertion Pitch	Tape Thickness
		A	B	F	T
CK1608 (0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
CK2125 (0805)	0.85 (0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
CKS2125 (0805)	0.85 (0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
CKP1608 (0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
LK1005 (0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
LK1608 (0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
LK2125 (0805)	0.85 (0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
HK0603 (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
HK1005 (0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
HK1608 (0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
HKQ0402 (01005)	0.2 (0.008)	0.25±0.04 (0.010±0.002)	0.45±0.04 (0.018±0.002)	2.0±0.05 (0.079±0.002)	0.36max (0.014max)
HKQ0603W (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
HKQ0603C (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
HKQ0603S (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
HKQ0603U (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
AQ105 (0402)	0.5 (0.020)	0.75±0.1 (0.030±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
BK0402 (01005)	0.2 (0.008)	0.25±0.04 (0.010±0.002)	0.45±0.04 (0.018±0.002)	2.0±0.05 (0.079±0.002)	0.36max (0.014max)
BK0603 (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
BK1005 (0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
BK1608 (0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BK2125 (0805)	0.85 (0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BK2010 (0804)	0.45 (0.018)	1.2±0.1 (0.047±0.004)	2.17±0.1 (0.085±0.004)	4.0±0.1 (0.157±0.004)	0.8max (0.031max)
BKP0402 (01005)	0.2 (0.008)	0.25±0.04 (0.010±0.002)	0.45±0.04 (0.018±0.002)	2.0±0.05 (0.079±0.002)	0.36max (0.014max)
BKP0603 (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
BKP1005 (0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
BKP1608 (0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BKP2125 (0805)	0.85 (0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BKH0603 (0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
BKH1005 (0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
MCF0605 (0202)	0.3 (0.012)	0.62±0.03 (0.024±0.001)	0.77±0.03 (0.030±0.001)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
MCFE1608 (0603)	0.65 (0.026)	1.1±0.05 (0.043±0.002)	1.9±0.05 (0.075±0.002)	4.0±0.1 (0.157±0.004)	0.72max (0.028max)

Unit : mm (inch)

● Embossed Tape (8mm wide)



Unit : mm (inch)

Type	Thickness mm (inch)	Chip cavity		Insertion Pitch F	Tape Thickness	
		A	B		K	T
CK2125 (0805)	1.25 (0.049)	1.5 ± 0.2 (0.059 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	2.0 (0.079)	0.3 (0.012)
CKS2125 (0805)	1.25 (0.049)	1.5 ± 0.2 (0.059 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	2.0 (0.079)	0.3 (0.012)
CKP2012 (0805)	0.9 (0.035)	1.55 ± 0.2 (0.061 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	1.3 (0.051)	0.3 (0.012)
CKP2016 (0806)	0.9 (0.035)	1.8 ± 0.1 (0.071 ± 0.004)	2.2 ± 0.1 (0.087 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	1.3 (0.051)	0.25 (0.01)
CKP2520 (1008)	0.7 (0.028)	2.3 ± 0.1 (0.091 ± 0.004)	2.8 ± 0.1 (0.110 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	1.4 (0.055)	0.3 (0.012)
	0.9 (0.035)				1.4 (0.055)	
	1.1 (0.043)				1.7 (0.067)	
NM2012 (0805)	0.9 (0.035)	1.55 ± 0.2 (0.061 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	1.3 (0.051)	0.3 (0.012)
NM2520 (1008)	0.9 (0.035)	2.3 ± 0.1 (0.091 ± 0.004)	2.8 ± 0.1 (0.110 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	1.4 (0.055)	0.3 (0.012)
	1.1 (0.043)				1.7 (0.067)	
LK2125 (0805)	1.25 (0.049)	1.5 ± 0.2 (0.059 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	2.0 (0.079)	0.3 (0.012)
HK2125 (0805)	0.85 (0.033)	1.5 ± 0.2 (0.059 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	1.5 (0.059)	0.3 (0.012)
	1.0 (0.039)				2.0 (0.079)	
BK2125 (0805)	1.25 (0.049)	1.5 ± 0.2 (0.059 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	2.0 (0.079)	0.3 (0.012)
BK3216 (1206)	0.8 (0.031)	1.9 ± 0.1 (0.075 ± 0.004)	3.5 ± 0.1 (0.138 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	1.4 (0.055)	0.3 (0.012)
MCF0806 (0302)	0.4 (0.016)	0.75 ± 0.05 (0.030 ± 0.002)	0.95 ± 0.05 (0.037 ± 0.002)	2.0 ± 0.05 (0.079 ± 0.002)	0.55 (0.022)	0.3 (0.012)
MCF1210 (0504)	0.55 (0.022)	1.15 ± 0.05 (0.045 ± 0.002)	1.40 ± 0.05 (0.055 ± 0.002)	4.0 ± 0.1 (0.157 ± 0.004)	0.65 (0.026)	0.3 (0.012)
MCF2010 (0804)	0.45 (0.018)	1.1 ± 0.1 (0.043 ± 0.004)	2.3 ± 0.1 (0.091 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	0.85 (0.033)	0.3 (0.012)
MCKK2012 (0805)	1.0 (0.039)	1.55 ± 0.2 (0.061 ± 0.008)	2.3 ± 0.2 (0.091 ± 0.008)	4.0 ± 0.1 (0.157 ± 0.004)	1.3 (0.051)	0.25 (0.010)

Unit : mm (inch)

Technical drawing of a mechanical part (Figure 1.10). The drawing shows a side view and a cross-section view. The side view includes dimensions and tolerances for various features:

- Overall length: 4.0 ± 0.05
- Overall width: 0.9 ± 0.05
- Distance from left end to first hole: 0.8 ± 0.04
- Distance between first and second hole: 1.0 ± 0.02
- Distance between second and third hole: 2.0 ± 0.04
- Distance from third hole to right end: 1.8 ± 0.02
- Distance from left end to first hole: F
- Distance between first and second hole: A
- Distance between second and third hole: B
- Feature labels: "Sprocket hole", "T", and "K".

Type	Thickness mm(inch)	Chip cavity		Insertion Pitch	Tape Thickness	
		A	B	F	K	T
HKQ0402 (01005)	0.2 (0.008)	0.23	0.43	1.0±0.02	0.5max.	0.25max.

The diagram shows a horizontal tape with four main sections labeled at the top: "Blank portion", "Chip cavity", "Blank portion", and "Leader". The tape has a series of circular holes along its top edge. Below the tape, three dimension lines indicate lengths: the first "Blank portion" is "160mm or more (6.3inches or more)"; the "Chip cavity" section is "100mm or more (3.94inches or more)"; and the final "Blank portion" is "400mm or more (15.7inches or more)". An arrow at the bottom points to the right, labeled "Direction of tape feed".

	t	W
4mm width tape	1.5max.	5±1.0
8mm width tape	2.5max.	10±1.5

A schematic diagram showing a top tape being pulled. A horizontal line represents the top tape, with an arrow pointing to it labeled "Top tape". Below it is another horizontal line labeled "Base tape". A diagonal line representing the pull direction is shown above the top tape, with an arrow pointing to it labeled "Pull direction". The angle between the pull direction and the top tape is indicated by a curved arrow and labeled $0 \sim 15^\circ$.

Multilayer chip inductors

Multilayer chip inductors for high frequency, Multilayer chip bead inductors

Multilayer common mode choke coils (MC series F type)

Metal Multilayer Chip Power Inductors (MCOIL™ MC series)

RELIABILITY DATA

1. Operating Temperature Range		
Specified Value	BK0402	-55 ~ +125°C
	BK0603	
	BK1005	
	BKH0603	
	BKH1005	
	BK1608	
	BK2125	
	ARRAY	
	BK2010	-55 ~ +85°C
	BK3216	
	BKP0402	
	BKP0603	
	BKP1005	
	BKP1608	
	BKP2125	
	MCF 0605	-40 ~ +85°C
	MCF 0806	
	MCF 1210	
	MCF 2010	
	CK1608	-40 ~ +85°C
	CK2125	
	CKS2125	
	CKP1608	
	CKP2012	
	CKP2016	
	CKP2520	
	NM2012	
	NM2520	
	LK1005	
	LK1608	
	LK2125	
	HKQ0402	-55 ~ +125°C
	HK0603	
	HK1005	
	HK1608	-40 ~ +85°C
	HK2125	
	HKQ0603W/HKQ0603C/HKQ0603S/ HKQ0603U/	-55 ~ +125°C
	AQ105	
	MCFE1608	-40 ~ +125°C (Including self-generated heat)
	MCKK2012	

2. Storage Temperature Range		
Specified Value	BK0402	-55 ~ +125°C
	BK0603	
	BK1005	
	BKH0603	
	BKH1005	
	BK1608	
	BK2125	
	ARRAY	BK2010
		BK3216
	BKP0402	-55 ~ +85°C
	BKP0603	
	BKP1005	
	BKP1608	
	BKP2125	
	MCF 0605	-40 ~ +85°C
	MCF 0806	
	MCF 1210	
	MCF 2010	
	CK1608	-40 ~ +85°C
	CK2125	
	CKS2125	
	CKP1608	
	CKP2012	
	CKP2016	
	CKP2520	
	NM2012	
	NM2520	
	LK1005	
	LK1608	
	LK2125	
	HKQ0402	-55 ~ +125°C
	HK0603	
	HK1005	-40 ~ +85°C
	HK1608	
	HK2125	-55 ~ +125°C
	HKQ0603W/HKQ0603C/HKQ0603S/ HKQ0603U/	
	AQ105	-40 ~ +85°C
	MCFE1608	
	MCKK2012	

3. Rated Current		
Specified Value	BK0402	150~750mA DC
	BK0603	100~500mA DC
	BK1005	120~1000mA DC
	BKH0603	115~450mA DC
	BKH1005	200~300mA DC
	BK1608	150~1500mA DC
	BK2125	200~1200mA DC
	ARRAY	BK2010 100mA DC
		BK3216 100~200mA DC
	BKP0402	0.55~1.1A DC
	BKP0603	0.8~1.8A DC
	BKP1005	0.8~2.4A DC
	BKP1608	1.0~3.0A DC
	BKP2125	1.5~4.0A DC
	MCF 0605	0.05A DC
	MCF 0806	0.1~0.13A DC
	MCF 1210	0.1~0.15A DC
	MCF 2010	0.1A DC
	CK1608	50~60mA DC
	CK2125	60~500mA DC
	CKS2125	110~280mA DC
	CKP1608	0.35~0.9A DC
	CKP2012	0.7~1.7A DC
	CKP2016	0.9~1.6A DC
	CKP2520	1.1~1.8A DC
	NM2012	1.0~1.2A DC
	NM2520	0.9~1.2A DC
	LK1005	20~25mA DC
	LK1608	1~150mA DC
	LK2125	5~300mA DC
	HK0603	60~470mA DC
	HK1005	110~300mA DC (−55~+125°C) 200~900mA DC (−55~+85°C)
	HK1608	150~300mA DC
	HK2125	300mA DC
	HKQ0402	100~500mA DC
	HKQ0603W	100~850mA DC
	HKQ0603C	160~850mA DC
	HKQ0603S	130~600mA DC
	HKQ0603U	190~900mA DC
	AQ105	280~710mA DC
	MCFE1608	Idc1 : 1400~2600mA DC, Idc2 : 800~1500mA DC
	MCKK2012	Idc1 : 2000mA DC, Idc2 : 1400mA DC

Definition of rated current:

- In the CK, CKS and BK Series, the rated current is the value of current at which the temperature of the element is increased within 20°C.
- In the BK Series P type, CK Series P type, NM Series, the rated current is the value of current at which the temperature of the element is increased within 40°C.
- In the LK, HK, HKQ0603, and AQ Series, the rated current is either the DC value at which the initial L value is decreased within 5% with the application of DC bias, or the value of current at which the temperature of the element is increased within 20°C.
- In the HKQ0402(~9N1), the rated current is either the DC value at which the initial L value is decreased within 5% with the application of DC bias, or the value of current at which the temperature of the element is increased within 20°C.
- In the HKQ0402(10N~), the rated current is either the DC value at which the initial L value is decreased within 5% with the application of DC bias, or the value of current at which the temperature of the element is increased within 25°C.
- In the MC Series, Idc1 is the DC value at which the initial L value is decreased within 30% and Idc2 is the DC value at which the temperature of element is increased within 40°C by the application of DC bias. (at 20°C)

4. Impedance			
Specified Value	BK0402		10~330 Ω ±5 Ω10 Ω, ±25%(Other)
	BK0603		10~1200 Ω ±25%
	BK1005		10~1800 Ω ±25%
	BKH0603		25~1500 Ω ±25%
	BKH1005		600~1800 Ω ±25%
	BK1608		22~2500 Ω ±25%
	BK2125		15~2500 Ω ±25%
	ARRAY	BK2010	5~1000 Ω ±25%
		BK3216	60~1000 Ω ±25%
	BKP0402		10~33 Ω ±5 Ω10 Ω, ±25%(Other)
	BKP0603		10~120 Ω ±5 Ω10 Ω, ±25%(Other)
	BKP1005		10~330 Ω ±5 ΩEM100), ±25%(Other)
	BKP1608		33~470 Ω ±25%
	BKP2125		33~330 Ω ±25%
	MCF 0605		12~90 Ω ±5 Ω12 Ω, ±20%(35 Ω, ±25%(Other)
	MCF 0806		12~90 Ω ±5 Ω12 Ω, ±20%(Other)
	MCF 1210		40~90 Ω ±20%(2H900), ±25%(Other)
	MCF 2010		90 Ω ±25%
	CK1608		—
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		
	LK1608		
	LK2125		
	HKQ0402		
	HK0603		
	HK1005		
	HK1608		
	HK2125		
	HKQ0603W/HKQ0603C/HKQ0603S/ HKQ0603U		
	AQ105		
	MCFE1608		
	MCKK2012		
Test Methods and Remarks	BK0402Series, BKP0402Series Measuring frequency : 100±1MHz Measuring equipment : E4991A(or its equivalent) Measuring jig : 16197A(or its equivalent)		
	BK0603Series, BKP0603Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent) Measuring jig : 16193A(or its equivalent)		
	BK1005Series, BKP1005Series ,BKH1005Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent) Measuring jig : 16192A(or its equivalent), 16193A(or its equivalent)		
	BK1608・2125Series, BKP1608・2125Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent), 4195A(or its equivalent) Measuring jig : 16092A(or its equivalent) or 16192A(or its equivalent)/HW		
	BK2010・3216Series, MCF Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent), 4195A(or its equivalent) Measuring jig : 16192A(or its equivalent)		

5. Inductance		
Specified Value	BK0402	
	BK0603	
	BK1005	
	BKH0603	
	BKH1005	
	BK1608	
	BK2125	
	ARRAY	BK2010 BK3216
	BKP0402	
	BKP0603	
	BKP1005	
	BKP1608	
	BKP2125	
	MCF 0605	
	MCF 0806	
	MCF 1210	
	MCF 2010	
	CK1608	4.7~10.0 μ H: $\pm$ 20%
	CK2125	0.1~10.0 μ H: $\pm$ 20%
	CKS2125	1.0~10.0 μ H: $\pm$ 20%
	CKP1608	0.33~2.2 μ H: $\pm$ 20%
	CKP2012	0.47~4.7 μ H: $\pm$ 20%
	CKP2016	0.47~4.7 μ H: $\pm$ 20%
	CKP2520	0.47~4.7 μ H: $\pm$ 20%
	NM2012	0.82~1.0 μ H: $\pm$ 20%
	NM2520	1.0~2.2 μ H: $\pm$ 20%
	LK1005	0.12~2.2 μ H: $\pm$ 10 or 20%
	LK1608	0.047~33.0 μ H: $\pm$ 20% 0.10~12.0 μ H: $\pm$ 10%
	LK2125	0.047~33.0 μ H: $\pm$ 20% 0.10~12.0 μ H: $\pm$ 10%
	HK0603	1.0~6.2nH: $\pm$ 0.3nH 6.8~100nH: $\pm$ 5%
	HK1005	1.0~6.2nH: $\pm$ 0.3nH 6.8~270nH: $\pm$ 5%
	HK1608	1.0~5.6nH: $\pm$ 0.3nH 6.8~470nH: $\pm$ 5%
	HK2125	1.5~5.6nH: $\pm$ 0.3nH 6.8~470nH: $\pm$ 5%
	HKQ0402	0.5~3.9nH: $\pm$ 0.1 or 0.2 or 0.3nH 4.3~5.6nH: $\pm$ 0.3nH or 3% or 5% 6.2~47nH: $\pm$ 3 or 5%
	HKQ0603W	0.6~3.9nH: $\pm$ 0.1 or 0.2 or 0.3nH 4.3~6.2nH: $\pm$ 0.2 or 0.3nH or 3 or 5% 6.8~27nH: $\pm$ 3 or 5% 33~100nH: $\pm$ 5%
	HKQ0603C	0.6~3.9nH: $\pm$ 0.1 or 0.2 or 0.3nH 4.3~6.2nH: $\pm$ 0.2 or 0.3nH 6.8~22nH: $\pm$ 3 or 5%
	HKQ0603S	0.6~6.2nH: $\pm$ 0.2 or 0.3nH 6.8~22nH: $\pm$ 3 or 5%
	HKQ0603U	0.6~4.2nH: $\pm$ 0.1 or 0.2 or 0.3nH 4.3~6.5nH: $\pm$ 0.2 or 0.3nH 6.8~22nH: $\pm$ 3 or 5%
	AQ105	1.0~6.2nH: $\pm$ 0.3nH 6.8~15nH: $\pm$ 5%
	MCFE1608	0.24~1.0 μ H: $\pm$ 20%
	MCKK2012	1.0 μ H: $\pm$ 20%
Test Methods and Remarks	CK、LK、CKP、NM、MC Series	
	Measuring frequency	: 2~4MHz (CK1608)
	Measuring frequency	: 2~25MHz (CK2125)
	Measuring frequency	: 2~10MHz (CKS2125)
	Measuring frequency	: 10~25MHz (LK1005)
	Measuring frequency	: 1~50MHz (LK1608)
	Measuring frequency	: 0.4~50MHz (LK2125)
	Measuring frequency	: 1MHz (CKP1608・CKP2012・CKP2016・CKP2520・NM2012・NM2520・MCFE1608・MCKK2012)
	Measuring equipment /jig	・4194A+16085B+16092A(or its equivalent) ・4195A+41951+16092A(or its equivalent) ・4294A+16192A(or its equivalent) ・4291A+16193A(or its equivalent)/LK1005 ・4285A+42841A+42842C+42851—61100(or its equivalent)/CKP1608・CKP2012・CKP2016・CKP2520・NM2012・NM2520・MCFE1608・MCKK2012
	Measuring current	・1mA rms(0.047~4.7 μ H) ・0.1mA rms(5.6~33 μ H)
	HK、HKQ、AQ Series	
	Measuring frequency	: 100MHz (HK0603・HK1005・AQ105)
	Measuring frequency	: 50/100MHz (HK1608・HK2125)
	Measuring frequency	: 500MHz (HKQ0603C・HKQ0603S・HKQ0603U)
	Measuring frequency	: 300/500MHz (HKQ0603W)
	Measuring frequency	: 100/500MHz (HKQ0402)
	Measuring equipment /jig	・4291A+16197A(or its equivalent)/HK0603・AQ105 ・4291A+16193A(or its equivalent)/HK1005 ・E4991A+16197A(or its equivalent)/HKQ0603S・HKQ0603U・HKQ0603W・HKQ0603C ・4291A+16092A + in-house made jig(or its equivalent)/HK1608・HK2125 ・E4991A+16196D(or its equivalent)/HKQ0402

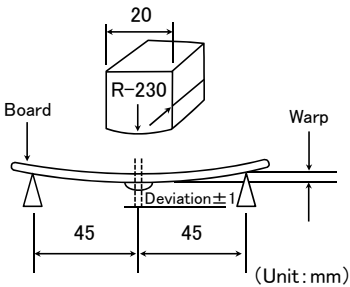
Specified Value	BK0402		—	
	BK0603			
	BK1005			
	BKH0603			
	BKH1005			
	BK1608			
	BK2125			
	ARRAY	BK2010		
		BK3216		
	BKP0402			
	BKP0603			
	BKP1005			
	BKP1608			
	BKP2125			
	MCF 0605			
	MCF 0806			
	MCF 1210			
	MCF 2010			
	CK1608			—
	CK2125			
	CKS2125			
	CKP1608			
	CKP2012			
	CKP2016			
	CKP2520			
	NM2012			
	NM2520			
	LK1005		10～20 min.	
	LK1608		10～35 min.	
	LK2125		15～50 min.	
	HK0603		4～5 min.	
	HK1005		8 min.	
	HK1608		8～12 min.	
	HK2125		10～18 min.	
	HKQ0402		3～8 min.	
	HKQ0603W		6～15 min.	
	HKQ0603C		14～15 min.	
	HKQ0603S		10～13 min.	
	HKQ0603U		14 min.	
	AQ105		8 min.	
	MCFE1608		—	
	MCKK2012			
Test Methods and Remarks	LK Series			
	Measuring frequency	: 10～25MHz (LK1005)		
	Measuring frequency	: 1～50MHz (LK1608)		
	Measuring frequency	: 0.4～50MHz (LK2125)		
	Measuring equipment /jig	: •4194A+16085B+16092A (or its equivalent) •4195A+41951+16092A (or its equivalent) •4294A+16192A (or its equivalent) •4291A+16193A (or its equivalent) /LK1005		
	Measuring current	: •1mA rms (0.047～4.7 μH) •0.1mA rms (5.6～33 μH)		
	HK、HKQ、AQ Series			
	Measuring frequency	: 100MHz (HK0603・HK1005・AQ105)		
	Measuring frequency	: 50/100MHz (HK1608・HK2125)		
	Measuring frequency	: 500MHz (HKQ0603C・HKQ0603S・HKQ0603U)		
	Measuring frequency	: 300/500MHz (HKQ0603W)		
	Measuring frequency	: 100/500MHz (HKQ0402)		
	Measuring equipment /jig	: •4291A+16197A (or its equivalent) /HK0603・AQ105 •4291A+16193A (or its equivalent) /HK1005 •E4991A+16197A (or its equivalent) /HKQ0603S・HKQ0603U・HKQ0603W・HKQ0603C •4291A+16092A + in-house made jig (or its equivalent) /HK1608, HK2125 •E4991A+16196D (or its equivalent) HKQ0402		

7. DC Resistance		
Specified Value	BK0402	0.07~1.2 Ω max.
	BK0603	0.065~1.50 Ω max.
	BK1005	0.03~0.90 Ω max.
	BKH0603	0.26~3.20 Ω max.
	BKH1005	0.85~2.00 Ω max.
	BK1608	0.05~1.10 Ω max.
	BK2125	0.05~0.75 Ω max.
	ARRAY	BK2010
		BK3216
	BKP0402	0.10~0.90 Ω max.
	BKP0603	0.15~0.80 Ω max.
	BKP1005	0.05~0.15 Ω max.
	BKP1608	0.030~0.180 Ω max.
	BKP2125	0.0273~0.220 Ω max.
	MCF 0605	0.025~0.18 Ω max.
	MCF 0806	0.020~0.075 Ω max.
	MCF 1210	2.5~6.5 Ω max.
	MCF 2010	2.5~5.0 Ω max.
	CK1608	2.5~4.5 Ω max.
	CK2125	4.5 Ω max.
	CKS2125	0.45~0.85 Ω (±30%)
	CKP1608	0.16~0.65 Ω max.
	CKP2012	0.12~0.52 Ω max.
	CKP2016	0.15~0.35 Ω max.
	CKP2520	0.08~0.28 Ω max.
	NM2012	0.075~0.20 Ω max.
	NM2520	0.05~0.16 Ω max.
	LK1005	0.10~0.15 Ω max.
	LK1608	0.11~0.22 Ω max.
	LK2125	0.41~1.16 Ω max.
	HK0603	0.2~2.2 Ω max.
	HK1005	0.1~1.1 Ω max.
	HK1608	0.11~3.74 Ω max.
	HK2125	0.08~4.8 Ω max.
	HKQ0402	0.05~2.6 Ω max.
	HKQ0603W	0.10~1.5 Ω max.
	HKQ0603C	0.08~5.0 Ω max.
	HKQ0603S	0.07~4.1 Ω max.
	HKQ0603U	0.07~1.6 Ω max.
	AQ105	0.06~1.29 Ω max.
	MCFE1608	0.06~1.29 Ω max.
	MCKK2012	0.07~0.45 Ω max.
		0.100~0.340 Ω max.
		0.123 Ω max.
Test Methods and Remarks	Measuring equipment: VOAC-7412, VOAC-7512, VOAC-7521 (made by Iwasaki Tsushinki), HIOKI3227 (or its equivalent)	

8. Self Resonance Frequency (SRF)				
Specified Value	BK0402		—	
	BK0603			
	BK1005			
	BKH0603			
	BKH1005			
	BK1608			
	BK2125			
	ARRAY	BK2010		
		BK3216		
	BKP0402			
	BKP0603			
	BKP1005			
	BKP1608			
	BKP2125			
	MCF 0605			
	MCF 0806			
	MCF 1210			
	MCF 2010			
	CK1608			17～25MHz min.
	CK2125			24～235MHz min.
	CKS2125			24～75MHz min.
	CKP1608			—
	CKP2012			
	CKP2016			
	CKP2520			
	NM2012			
	NM2520			
	LK1005			40～180MHz min.
	LK1608			9～260MHz min.
	LK2125			13～320MHz min.
	HK0603			900～10000MHz min.
	HK1005			400～10000MHz min.
	HK1608			300～10000MHz min.
	HK2125			200～4000MHz min.
	HKQ0402			1200～10000MHz min.
	HKQ0603W			800～10000MHz min.
	HKQ0603C			2500～10000MHz min.
	HKQ0603S			1900～10000MHz min.
	HKQ0603U			1900～10000MHz min.
	AQ105			2300～10000MHz min.
	MCFE1608			—
	MCKK2012			
Test Methods and Remarks	LK、CK Series : Measuring equipment : 4195A (or its equivalent) Measuring jig : 41951 + 16092A (or its equivalent) HK、HKQ、AQ Series : Measuring equipment : 8719C (or its equivalent)・8753D (or its equivalent) / HK2125			

9. Temperature Characteristic			
Specified Value	BK0402		—
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		
	LK1608		
	LK2125		
	HK0603		
	HK1005		
	HK1608		
	HK2125		
HKQ0402			
HKQ0603W			
HKQ0603C			
HKQ0603S			
HKQ0603U			
AQ105			
MCFE1608			
MCKK2012			
Test Methods and Remarks	HK、HKQ、AQ Series:		
	Temperature range	: −30~+85℃	
	Reference temperature	: +20℃	
	MC Series:		
	Temperature range	: −40~+85℃	
	Reference temperature	: +20℃	

10. Resistance to Flexure of Substrate

Specified Value	BK0402	No mechanical damage.
	BK0603	
	BK1005	
	BKH0603	
	BKH1005	
	BK1608	
	BK2125	
	ARRAY	
	BK2010	
	BK3216	
	BKP0402	
	BKP0603	
	BKP1005	
	BKP1608	
	BKP2125	
	MCF 0605	
	MCF 0806	
	MCF 1210	
	MCF 2010	
	CK1608	
	CK2125	
	CKS2125	
	CKP1608	
	CKP2012	
	CKP2016	
	CKP2520	
	NM2012	
	NM2520	
	LK1005	
	LK1608	
	LK2125	
	HK0603	
	HK1005	
	HK1608	
	HK2125	
	HKQ0402	
	HKQ0603W	
	HKQ0603C	
	HKQ0603S	
	HKQ0603U	
	AQ105	
	MCFE1608	
	MCKK2012	
Test Methods and Remarks	Warp	: 2mm (BK Series without 0402size, BKP, BKH1005, CK, CKS, CKP, NM, LK, HK, HKQ0603S, HKQ0603U, AQ Series, MCF1210, MC Series)
	Testing board	: 1mm (BK0402, BKP0402, BKH0603, HKQ0402, HKQ0603W, HKQ0603C Series, MCF Series without 1210 size,)
	Thickness	: glass epoxy-resin substrate
		: 0.8mm
		
	(Unit: mm)	

11. Solderability					
Specified Value	BK0402		At least 75% of terminal electrode is covered by new solder.		
	BK0603				
	BK1005				
	BKH0603				
	BKH1005				
	BK1608				
	BK2125				
	ARRAY	BK2010			
		BK3216			
	BKP0402				
	BKP0603				
	BKP1005				
	BKP1608				
	BKP2125				
	MCF 0605				
	MCF 0806				
	MCF 1210				
	MCF 2010				
	Specified Value	CK1608		At least 75% of terminal electrode is covered by new solder.	
		CK2125			
CKS2125					
CKP1608					
CKP2012					
CKP2016					
CKP2520					
NM2012					
NM2520					
LK1005					
LK1608					
LK2125					
HK0603					
HK1005					
HK1608					
HK2125					
HKQ0402					
HKQ0603W					
HKQ0603C					
HKQ0603S					
HKQ0603U					
AQ105					
MCFE1608					
MCKK2012					
Test Methods and Remarks	Solder temperature	: 230±5℃ (JIS Z 3282 H60A or H63A)			
	Solder temperature	: 245±3℃ (Sn/3.0Ag/0.5Cu)			
	Duration	: 4±1 sec.			

12. Resistance to Soldering			
Specified Value	BK0402		Appearance : No significant abnormality Impedance change : Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		Appearance : No significant abnormality Impedance change : Within ±20%
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		No mechanical damage. Remaining terminal electrode : 70% min
	CK2125		
	CKS2125		
	CKP1608		Inductance change R10~4R7 : Within ±10% 6R8~100 : Within ±15% CKS2125 : Within ±20% CKP1608、CKP2012、CKP2016、CKP2520、NM2012、NM2520 : Within ±30%
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		No mechanical damage. Remaining terminal electrode : 70% min. Inductance change : Within ±15%
	LK1608		No mechanical damage.
	LK2125		Remaining terminal electrode : 70% min. Inductance change 47N~4R7 : Within ±10% 5R6~330 : Within ±15%
	HK0603		No mechanical damage. Remaining terminal electrode : 70% min. Inductance change : Within ±5%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603C		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFE1608		No mechanical damage.
	MCKK2012		Remaining terminal electrode : 70% min. Inductance change : Within ±10%
Test Methods and Remarks	Solder temperature	: 260±5℃	
	Duration	: 10±0.5 sec.	
	Preheating temperature	: 150 to 180℃	
	Preheating time	: 3 min.	
	Flux	: Immersion into methanol solution with colophony for 3 to 5 sec.	
	Recovery	: 2 to 3 hrs of recovery under the standard condition after the test. (See Note 1)	
(Note 1) When there are questions concerning measurement result; measurement shall be made after 48±2 hrs of recovery under the standard condition.			

13. Thermal Shock			
Specified Value	BK0402		Appearance: No significant abnormality Impedance change: Within $\pm 30\%$
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		Appearance: No significant abnormality Impedance change: Within $\pm 20\%$
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		No mechanical damage.
	CK2125		Inductance change: Within $\pm 20\%$ Q change: Within $\pm 30\%$
	CKS2125		Inductance change: Within $\pm 20\%$ (CKS2125)
	CKP1608		No mechanical damage. Inductance change: Within $\pm 30\%$
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		No mechanical damage. Inductance change: Within $\pm 10\%$ Q change: Within $\pm 30\%$
	LK1608		
	LK2125		
	HK0603		No mechanical damage. Inductance change: Within $\pm 10\%$ Q change: Within $\pm 20\%$
	HK1005		
	HK1608		
	HK2125		
HKQ0402			
HKQ0603W			
HKQ0603C			
HKQ0603S			
HKQ0603U			
AQ105			
MCFE1608		Appearance: No significant abnormality	
MCKK2012		Inductance change: Within $\pm 10\%$	
Test Methods and Remarks	Conditions for 1 cycle		
	Step	temperature (°C)	time (min.)
	1	Minimum operating temperature $+0/-3$	30 ± 3
	2	Room temperature	$2 \sim 3$
	3	Maximum operating temperature $+3/-0$	30 ± 3
	4	Room temperature	$2 \sim 3$
	Number of cycles: 5		
Recovery: 2 to 3 hrs of recovery under the standard condition after the test. (See Note 1)			
(Note 1) When there are questions concerning measurement result; measurement shall be made after 48 ± 2 hrs of recovery under the standard condition.			

14. Damp Heat (Steady state)			
Specified Value	BK0402		Appearance: No significant abnormality Impedance change: Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		No mechanical damage.
	CK2125		Inductance change: Within ±20% Q change: Within ±30%
	CKS2125		Inductance change: Within ±20%
	CKP1608		No mechanical damage. Inductance change: Within ±30%
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		No mechanical damage.
	LK1608		Inductance change: Within ±10% Q change: Within ±30%
	LK2125		No mechanical damage.
			Inductance change: Within ±20% Q change: Within ±30%
	HK0603		No mechanical damage. Inductance change: Within ±10% Q change: Within ±20%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603C		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MC1608		Appearance: No significant abnormality Inductance change: Within ±10%
	MC2012		
Test Methods and Remarks	BK, BKP, BKH Series, MCF Series: Temperature : 40±2°C Humidity : 90 to 95%RH Duration : 500+24/—0 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber. (See Note 1)		
	LK, CK, CKS, CKP, NM, HK, HKQ, AQ, MC Series: Temperature : 40±2°C (LK, CK, CKS, CKP, NM Series) : 60±2°C (HK, HKQ, AQ, MC Series) Humidity : 90 to 95%RH Duration : 500±12 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber. (See Note 1)		
(Note 1) When there are questions concerning measurement result; measurement shall be made after 48±2 hrs of recovery under the standard condition.			

15. Loading under Damp Heat			
Specified Value	BK0402		Appearance: No significant abnormality Impedance change: Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	CK1608		
	CK2125		Inductance change: Within ±20% Q change: Within ±30%
	CKS2125		No mechanical damage.
			Inductance change: Within ±20%
	CKP1608		No mechanical damage. Inductance change: Within ±30%
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		No mechanical damage.
			Inductance change: Within ±10% Q change: Within ±30%
	LK1608		No mechanical damage.
			Inductance change: 0.047~12.0 μH: Within ±10% 15.0~33.0 μH: Within ±15%
			Q change: Within ±30%
	LK2125		No mechanical damage.
			Inductance change: Within ±20% Q change: Within ±30%
	HK0603		No mechanical damage. Inductance change: Within ±10% Q change: Within ±20%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603C		
	HKQ0603S		
HKQ0603U			
AQ105			
MCFE1608		Appearance: No significant abnormality	
MCKK2012		Inductance change: Within ±10%	
Test Methods and Remarks	BK, BKP, BKH Series: Temperature : 40±2℃ Humidity : 90 to 95%RH Applied current : Rated current Duration : 500+24/—0 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.(See Note 1)		
	LK, CK, CKS, CKP, NK, HK, HKQ, AQ, MC Series: Temperature : 40±2℃(LK, CK, CKS, CKP, NM Series) : 60±2℃(HK, HKQ, AQ, MC Series) Humidity : 90 to 95%RH Applied current : Rated current Duration : 500±12 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.(See Note 1)		
Note on standard condition: “standard condition” referred to herein is defined as follows: 5 to 35℃ of temperature, 45 to 85% relative humidity, and 86 to 106kPa of air pressure. When there are questions concerning measurement results: In order to provide correlation data, the test shall be conducted under condition of 20±2℃ of temperature, 60 to 70% relative humidity, and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the “standard condition.” (Note 1) Measurement shall be made after 48±2 hrs of recovery under the standard condition.			

16. Loading at High Temperature			
Specified Value	BK0402		Appearance: No significant abnormality Impedance change: Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		No mechanical damage.
	CK2125		Inductance change: Within ±20% Q change: Within ±30%
	CKS2125		No mechanical damage.
			Inductance change: Within ±20%
	CKP1608		No mechanical damage. Inductance change: Within ±30%
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		No mechanical damage. Inductance change: Within ±10% Q change: Within ±30%
	LK1608		No mechanical damage. Inductance change: 0.047~12.0 μH: Within ±10% 15.0~33.0 μH: Within ±15% Q change: Within ±30%
	LK2125		No mechanical damage. Inductance change: Within ±20% Q change: Within ±30%
	HK0603		No mechanical damage. Inductance change: Within ±10% Q change: Within ±20%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603C		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFE1608		Appearance: No significant abnormality Inductance change: Within ±10%
	MCKK2012		
Test Methods and Remarks	BK, BKH, BKP Series, MCF Series: Temperature : 125±3℃ (BK, BKH Series) : 85±3℃ (BKP, MCF Series) Applied current : Rated current Duration : 500+24/—0 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber. (See Note 1)		
	LK, CK, CKS, CKP, NM, HK, HKQ, AQ, MC Series: Temperature : 85±2℃ (LK, CK, CKS, CKP, NM, MC Series) : 85±2℃ (HK1608, 2125) : 85±2℃ (HK1005, AQ105 operating temperature range—55~+85℃) : 125±2℃ (HKQ0402, HK0603, HK1005, HKQ0603S, HKQ0603U, HKQ0603W, HKQ0603C, AQ105 operating temperature range—55~+125℃) Applied current : Rated current Duration : 500±12 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the test. (See Note 1)		
Note on standard condition: "standard condition" referred to herein is defined as follows: 5 to 35℃ of temperature, 45 to 85% relative humidity, and 86 to 106kPa of air pressure. When there are questions concerning measurement results: In order to provide correlation data, the test shall be conducted under condition of 20±2℃ of temperature, 60 to 70% relative humidity, and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the "standard condition." (Note 1) Measurement shall be made after 48+2 hrs of recovery under the standard condition			

Precautions on the use of Multilayer chip inductors

Multilayer chip inductors for high frequency, Multilayer chip bead inductors

Multilayer common mode choke coils(MC series F type)

Metal Multilayer Chip Power Inductors (MCOIL™ MC series)

■ PRECAUTIONS

1. Circuit Design

Precautions	◆ Verification of operating environment, electrical rating and performance 1. A malfunction in medical equipment, spacecraft, nuclear reactors, etc. may cause serious harm to human life or have severe social ramifications. As such, any inductors to be used in such equipment may require higher safety and/or reliability considerations and should be clearly differentiated from components used in general purpose applications.
	◆ Operating Current (Verification of Rated current) 1. The operating current for inductors must always be lower than their rated values. 2. Do not apply current in excess of the rated value because the inductance may be reduced due to the magnetic saturation effect.

2. PCB Design

Precautions	◆ Pattern configurations (Design of Land-patterns) 1. When inductors are mounted on a PCB, the size of land patterns and the amount of solder used (size of fillet) can directly affect inductor performance. Therefore, the following items must be carefully considered in the design of solder land patterns: (1) The amount of solder applied can affect the ability of chips to withstand mechanical stresses which may lead to breaking or cracking. Therefore, when designing land-patterns it is necessary to consider the appropriate size and configuration of the solder pads which in turn determines the amount of solder necessary to form the fillets. (2) When more than one part is jointly soldered onto the same land or pad, the pad must be designed so that each component's soldering point is separated by solder-resist. (3) The larger size of land patterns and amount of solder, the smaller Q value after mounting on PCB. It makes higher the Q value to design land patterns smaller than terminal electrode of chips.
	◆ Pattern configurations (Inductor layout on panelized [breakaway] PC boards) 1. After inductors have been mounted on the boards, chips can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering the reflow soldered boards etc.) For this reason, planning pattern configurations and the position of SMD inductors should be carefully performed to minimize stress.

◆ Pattern configurations (Design of Land-patterns)

1. The following diagrams and tables show some examples of recommended patterns to prevent excessive solder amounts (larger fillets which extend above the component end terminations). Examples of improper pattern designs are also shown.

(1) Recommended land dimensions for a typical chip inductor land patterns for PCBs

Recommended land dimensions for wave-soldering (Unit:mm)

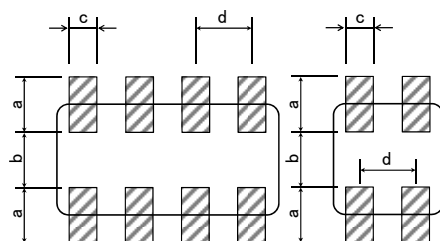
Type	1608	2012	2125	2016	2520	3216
Size	L	1.6	2.0	2.0	2.0	3.2
	W	0.8	1.25	1.25	1.6	2.0
A	0.8~1.0	1.0~1.4	1.0~1.4	1.0~1.4	1.0~1.4	1.8~2.5
B	0.5~0.8	0.8~1.5	0.8~1.5	0.8~1.5	0.6~1.0	0.8~1.7
C	0.6~0.8	0.9~1.2	0.9~1.2	1.3~1.6	1.6~2.0	1.2~1.6

Recommended land dimensions for reflow-soldering (Unit:mm)

Type	0402	0603	1005	105	1608	2012	2125	2016	2520	3216
Size	L	0.4	0.6	1.0	1.0	1.6	2.0	2.0	2.5	3.2
	W	0.2	0.3	0.5	0.6	0.8	1.25	1.25	1.6	1.6
A	0.15~0.25	0.20~0.30	0.45~0.55	0.50~0.55	0.8~1.0	0.8~1.2	0.8~1.2	0.8~1.2	1.0~1.4	1.8~2.5
B	0.10~0.20	0.20~0.30	0.40~0.50	0.30~0.40	0.6~0.8	0.8~1.2	0.8~1.2	0.8~1.2	0.6~1.0	0.6~1.5
C	0.15~0.30	0.25~0.40	0.45~0.55	0.60~0.70	0.6~0.8	0.9~1.6	0.9~1.6	1.2~2.0	1.8~2.2	1.2~2.0

Technical
considerations

Excess solder can affect the ability of chips to withstand mechanical stresses. Therefore, please take proper precautions when designing land-patterns.



Recommended land dimension for Reflow-soldering

Type		3216	2010	1210	0806	0605
Size	L	3.2	2.0	1.25	0.85	0.65
	W	1.6	1.0	1.0	0.65	0.50
a		0.7~0.9	0.5~0.6	0.45~0.55	0.25~0.35	0.27~0.33
b		0.8~1.0	0.5~0.6	0.7~0.8	0.25~0.35	0.17~0.23
c		0.4~0.5	0.2~0.3	0.25~0.35	0.25~0.35	0.20~0.26
d		0.8	0.5	0.55	0.5	0.4

(Unit: mm)

((2) Examples of good and bad solder application

Item	Not recommended	Recommended
Mixed mounting of SMD and leaded components		
Component placement close to the chassis		
Hand-soldering of leaded components near mounted components		
Horizontal component placement		

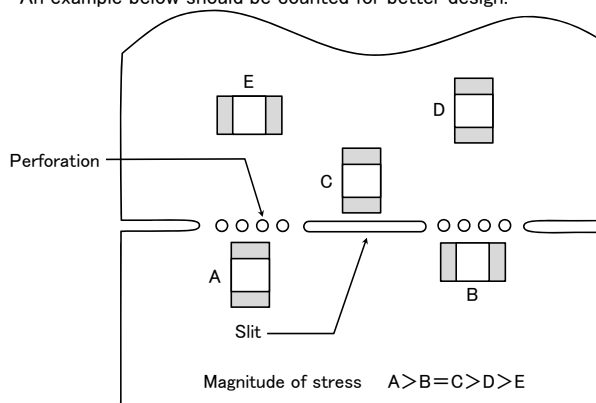
◆Pattern configurations (Inductor layout on panelized[breakaway] PC boards)

1-1. The following are examples of good and bad inductor layout; SMD inductors should be located to minimize any possible mechanical stresses from board warp or deflection.

Item	Not recommended	Recommended
Deflection of the board		

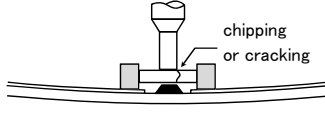
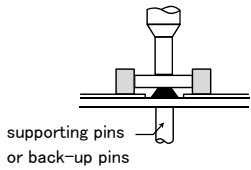
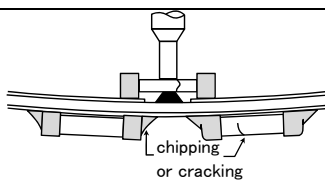
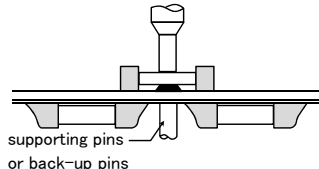
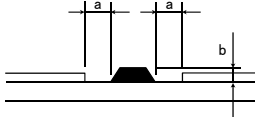
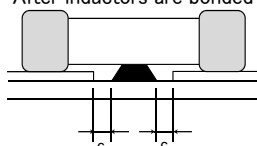
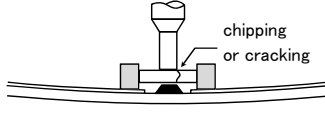
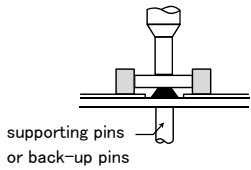
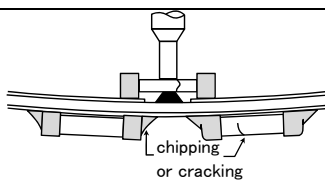
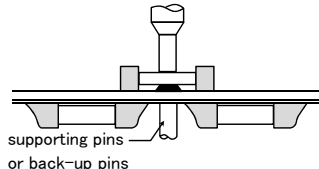
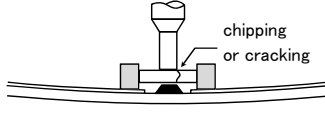
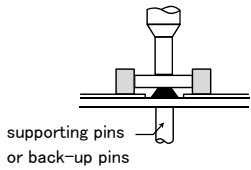
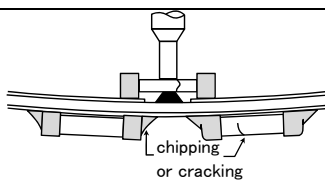
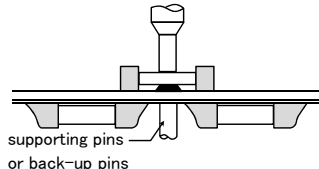
1-2. To layout the inductors for the breakaway PC board, it should be noted that the amount of mechanical stresses given will vary depending on inductor layout.

An example below should be counted for better design.



1-3. When breaking PC boards along their perforations, the amount of mechanical stress on the inductors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, any ideal SMD inductor layout must also consider the PCB splitting procedure.

3. Considerations for automatic placement

Precautions	◆Adjustment of mounting machine - Excessive impact load should not be imposed on the inductors when mounting onto the PC boards. - The maintenance and inspection of the mounter should be conducted periodically. ◆Selection of Adhesives - Mounting inductors with adhesives in preliminary assembly, before the soldering stage, may lead to degraded inductor characteristics unless the following factors are appropriately checked; the size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, it is imperative to consult the manufacturer of the adhesives on proper usage and amounts of adhesive to use.																	
Technical considerations	◆Adjustment of mounting machine - If the lower limit of the pick-up nozzle is low, too much force may be imposed on the inductors, causing damage. To avoid this, the following points should be considered before lowering the pick-up nozzle: - The lower limit of the pick-up nozzle should be adjusted to the surface level of the PC board after correcting for deflection of the board. - The pick-up pressure should be adjusted between 1 and 3N static loads. - To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins should be used under the PC board. The following diagrams show some typical examples of good pick-up nozzle placement: <table><tr><th>Item</th><th>Improper method</th><th>Proper method</th></tr><tr><td>Single-sided mounting</td><td></td><td></td></tr><tr><td>Double-sided mounting</td><td></td><td></td></tr></table> - As the alignment pin wears out, adjustment of the nozzle height can cause chipping or cracking of the inductors because of mechanical impact on the inductors. To avoid this, the monitoring of the width between the alignment pin in the stopped position, and maintenance, inspection and replacement of the pin should be conducted periodically. ◆Selection of Adhesives - Some adhesives may cause reduced insulation resistance. The difference between the shrinkage percentage of the adhesive and that of the inductors may result in stresses on the inductors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect component placement, so the following precautions should be noted in the application of adhesives. - Required adhesive characteristics - The adhesive should be strong enough to hold parts on the board during the mounting & solder process. - The adhesive should have sufficient strength at high temperatures. - The adhesive should have good coating and thickness consistency. - The adhesive should be used during its prescribed shelf life. - The adhesive should harden rapidly. - The adhesive must not be contaminated. - The adhesive should have excellent insulation characteristics. - The adhesive should not be toxic and have no emission of toxic gasses. - When using adhesives to mount inductors on a PCB, inappropriate amounts of adhesive on the board may adversely affect component placement. Too little adhesive may cause the inductors to fall off the board during the solder process. Too much adhesive may cause defective soldering due excessive flow of adhesive on to the land or solder pad. [Recommended conditions] <table><tr><th>Figure</th><th>0805 case sizes as examples</th></tr><tr><td>a</td><td>0.3mm min</td></tr><tr><td>b</td><td>100~120 μm</td></tr><tr><td>c</td><td>Area with no adhesive</td></tr></table> Amount of adhesives  After inductors are bonded 	Item	Improper method	Proper method	Single-sided mounting			Double-sided mounting			Figure	0805 case sizes as examples	a	0.3mm min	b	100~120 μm	c	Area with no adhesive
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4. Soldering

Precautions	◆Selection of Flux - Since flux may have a significant effect on the performance of inductors, it is necessary to verify the following conditions prior to use; - Flux used should be with less than or equal to 0.1 wt% (Chlorine conversion method) of halogenated content. Flux having a strong acidity content should not be applied. - When soldering inductors on the board, the amount of flux applied should be controlled at the optimum level. - When using water-soluble flux, special care should be taken to properly clean the boards. ◆Soldering - Temperature, time, amount of solder, etc. are specified in accordance with the following recommended conditions, and please contact us about peak temperature when you use lead-free paste.
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◆ Selection of Flux

- 1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate the flux, or highly acidic flux is used, an excessive amount of residue after soldering may lead to corrosion of the terminal electrodes or degradation of insulation resistance on the surface of the Inductor.
- 1-2. Flux is used to increase solderability in flow soldering, but if too much is applied, a large amount of flux gas may be emitted and may detrimentally affect solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved by water content in the air, the residue on the surface of Inductor in high humidity conditions may cause a degradation of insulation resistance and therefore affect the reliability of the components. The cleaning methods and the capability of the machines used should also be considered carefully when selecting water-soluble flux.

◆ Soldering

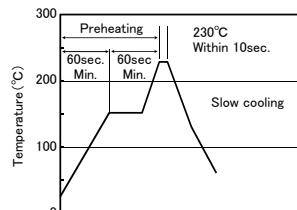
1-1. Preheating when soldering

Heating: Chip inductor components should be preheated to within 100 to 130°C of the soldering. Cooling: The temperature difference between the components and cleaning process should not be greater than 100°C.

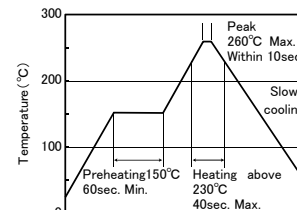
Chip inductors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling. Therefore, the soldering process must be conducted with a great care so as to prevent malfunction of the components due to excessive thermal shock.

[Reflow soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】

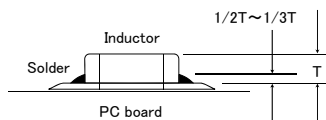


※Ceramic chip components should be preheated to within 100 to 130°C of the soldering.

※Assured to be reflow soldering for 2 times.

Caution

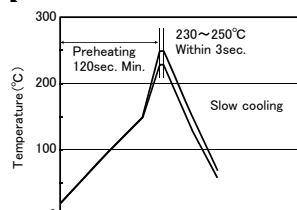
1. The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of the inductor, as shown below:



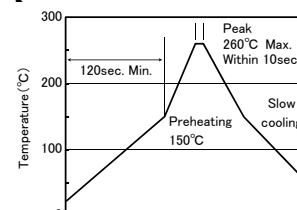
2. Because excessive dwell times can detrimentally affect solderability, soldering duration should be kept as close to recommended times as possible.

[Wave soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】



※Ceramic chip components should be preheated to within 100 to 130°C of the soldering.

※Assured to be wave soldering for 1 time.

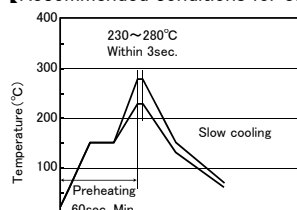
※Except for reflow soldering type.

Caution

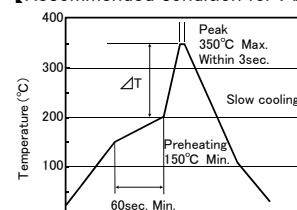
1. Make sure the inductors are preheated sufficiently.
2. The temperature difference between the inductor and melted solder should not be greater than 100 to 130°C.
3. Cooling after soldering should be as gradual as possible.
4. Wave soldering must not be applied to the inductors designated as for reflow soldering only.

[Hand soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】



(※ $\Delta T \leq 190^\circ\text{C}$ (3216 Type max), $\Delta T \leq 130^\circ\text{C}$ (3225 Type min))

※It is recommended to use 20W soldering iron and the tip is 1 φ or less.

※The soldering iron should not directly touch the components.

※Assured to be soldering iron for 1 time.

Note: The above profiles are the maximum allowable soldering condition, therefore these profiles are not always recommended.

Technical
considerations

	Caution 1. Use a 20W soldering iron with a maximum tip diameter of 1.0 mm. 2. The soldering iron should not directly touch the inductor.						
5. Cleaning							
Precautions	◆Cleaning conditions 1. When cleaning the PC board after the Inductors are all mounted, select the appropriate cleaning solution according to the type of flux used and purpose of the cleaning (e.g. to remove soldering flux or other materials from the production process.) 2. Cleaning conditions should be determined after verifying, through a test run, that the cleaning process does not affect the inductor's characteristics.						
Technical considerations	◆Cleaning conditions 1. The use of inappropriate solutions can cause foreign substances such as flux residue to adhere to the inductor, resulting in a degradation of the inductor's electrical properties (especially insulation resistance). 2. Inappropriate cleaning conditions (insufficient or excessive cleaning) may detrimentally affect the performance of the inductors. (1) Excessive cleaning a. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of the PC board which may lead to the cracking of the inductor or the soldered portion, or decrease the terminal electrodes' strength. Thus the following conditions should be carefully checked; <table> <tr> <td>Ultrasonic output</td><td>Below 20W/l</td></tr> <tr> <td>Ultrasonic frequency</td><td>Below 40kHz</td></tr> <tr> <td>Ultrasonic washing period</td><td>5 min. or less</td></tr> </table>	Ultrasonic output	Below 20W/l	Ultrasonic frequency	Below 40kHz	Ultrasonic washing period	5 min. or less
Ultrasonic output	Below 20W/l						
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6. Post cleaning processes							
Precautions	◆Application of resin coatings, moldings, etc. to the PCB and components. 1. With some type of resins a decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the inductor's performance. 2. When a resin's hardening temperature is higher than the inductor's operating temperature, the stresses generated by the excess heat may lead to inductor damage or destruction. 3. Stress caused by a resin's temperature generated expansion and contraction may damage inductors. The use of such resins, molding materials etc. is not recommended.						
7. Handling							
Precautions	◆Breakaway PC boards (splitting along perforations) 1. When splitting the PC board after mounting inductors and other components, care is required so as not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices. ◆General handling precautions 1. Always wear static control bands to protect against ESD. 2. Keep the inductors away from all magnets and magnetic objects. 3. Use non-magnetic tweezers when handling inductors. 4. Any devices used with the inductors (soldering irons, measuring instruments) should be properly grounded. 5. Keep bare hands and metal products (i.e., metal desk) away from chip electrodes or conductive areas that lead to chip electrodes. 6. Keep inductors away from items that generate magnetic fields such as speakers or coils. ◆Mechanical considerations 1. Be careful not to subject the inductors to excessive mechanical shocks. (1) If inductors are dropped on the floor or a hard surface they should not be used. (2) When handling the mounted boards, be careful that the mounted components do not come in contact with or bump against other boards or components.						
8. Storage conditions							
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep the packaging material in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible. Recommended conditions Ambient temperature Below 30°C Humidity Below 70% RH The ambient temperature must be kept below 40°C. Even under ideal storage conditions inductor electrode solderability decreases as time passes, so inductors should be used within 6 months from the time of delivery. *The packaging material should be kept where no chlorine or sulfur exists in the air.						
Technical considerations	◆Storage 1. If the parts are stocked in a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/package materials may take place. For this reason, components should be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the inductors.						